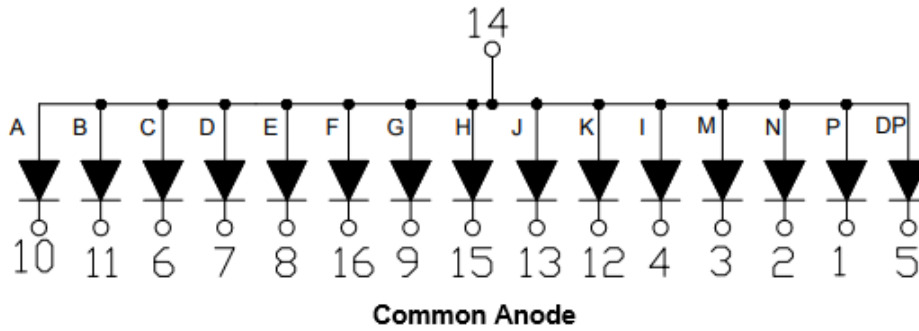
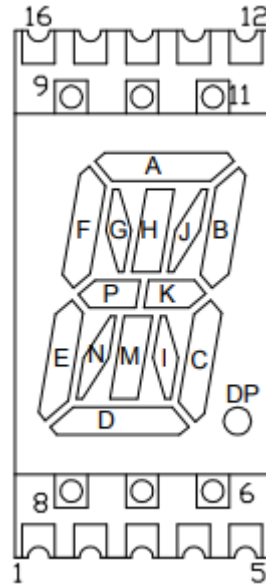




**TYPICAL INTERNAL EQUIVALENT CIRCUIT**



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**ABSOLUTE MAXIMUM RATINGS**
**(TA=25°C)**

Parameter	Symbol	Max Rating	Unit
Power Dissipation	PD	70	mW
Pulse Forward Current	IFP	90	mA
Continuous Forward Current	IF	25	mA
Reverse Voltage Segment	VR	5	V
Operating Temperature Range	TOPR	-40~+105	°C
Storage Temperature Range	TSTG	-40~+105	°C
IFP = Pulse Width ≤ 10 ms, Duty Ratio ≤1/10. Soldering Condition: 260 °C/ 5sec			

**OPTICAL-ELECTRICAL CHARACTERISTICS**
**(TA=25°C)**

Parameter	Symbol	Test Condition	Value			Unit
			Min	Typ	Max	
Luminous Intensity	IV	IF = 20mA	-	15	-	mcd
Forward Voltage (Per Dice)	VF	IF = 20mA	-	2.0	2.8	V
Reverse Leakage Current	IR	VR = 5V	-	-	100	µA
Dominant Wavelength	λd	IF = 20mA	-	590	-	nm
Peak Wavelength	Δp	IF = 20mA	-	592	-	nm



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## OPTICAL CHARACTERISTIC CURVES

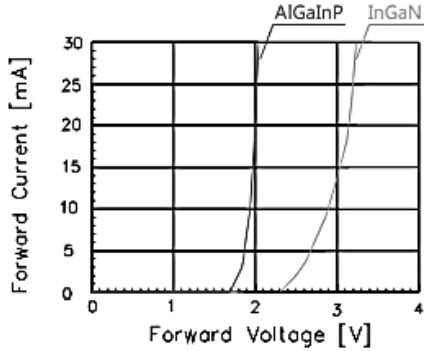


Fig 1. Forward Current vs. Forward Voltage

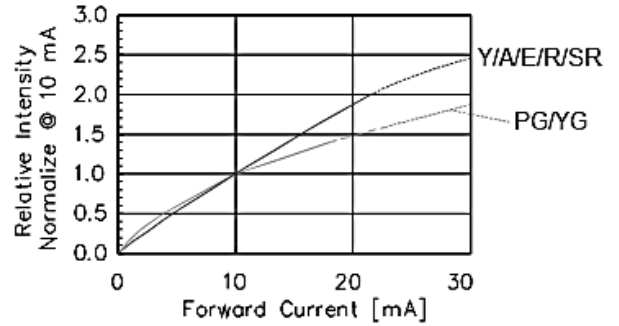


Fig 2. Relative Intensity vs. Forward Current

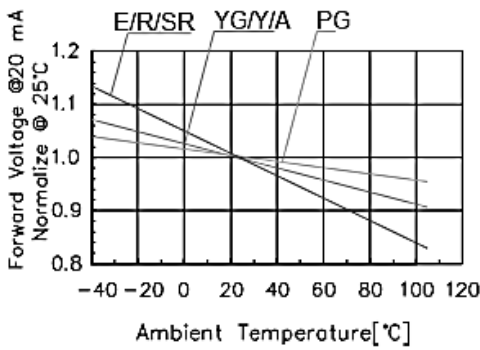


Fig 3. Forward Voltage vs. Temperature

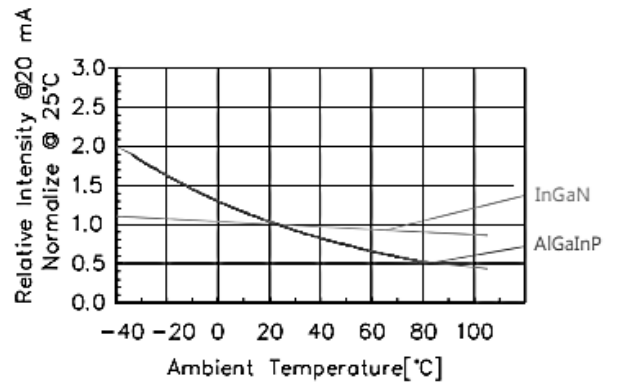


Fig 4. Relative Intensity vs. Temperature

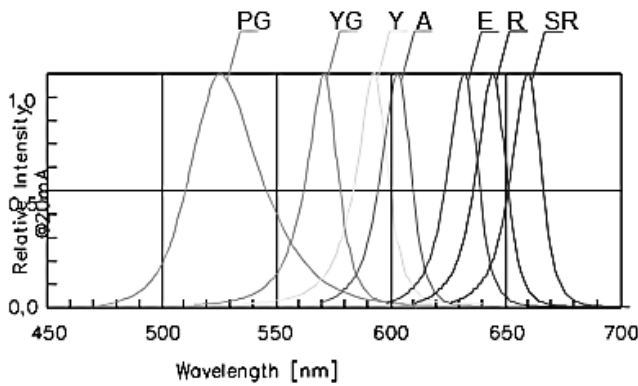


Fig 5. Relative Intensity vs. Wavelength

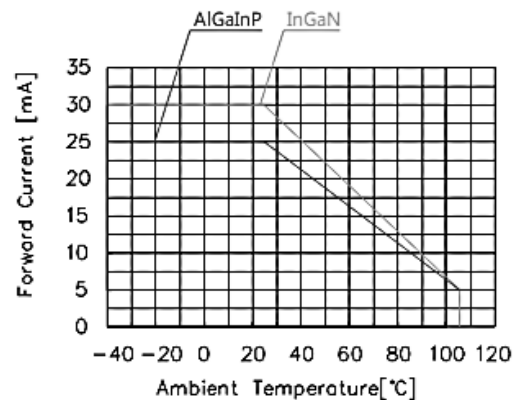


Fig 6. Forward current vs. Temperature

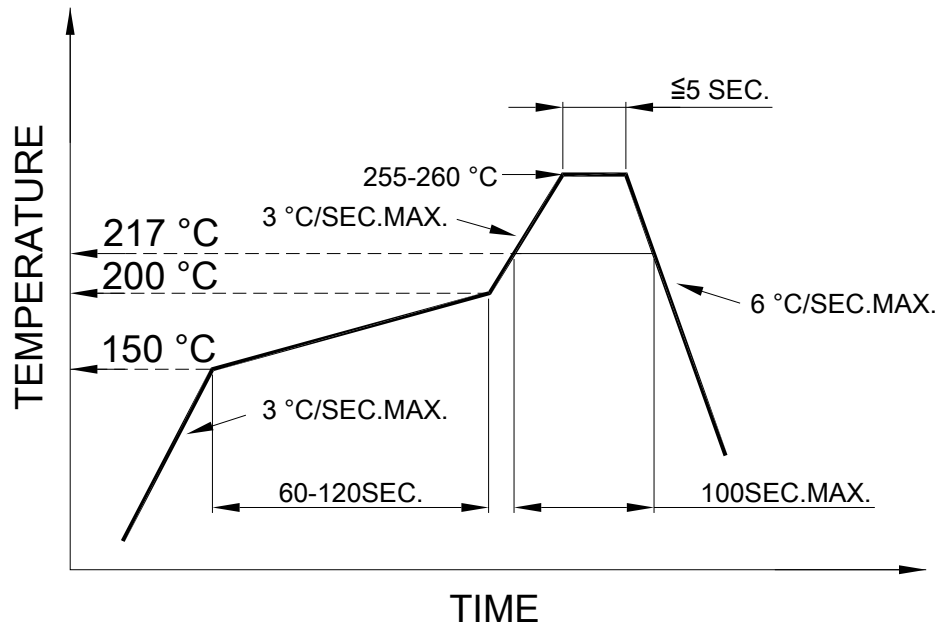


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**SOLDERING CONDITIONS – DISPLAY TYPE LED**
**● SMT REFLOW SOLDERING INSTRUCTIONS**

SMT Soldering Profile

Pb free reflow soldering Profile


**● SOLDERING IRON**

Basic spec is  $\leq 4$  sec when 260°C. If temperature is higher, time should be shorter (+10°C → 1 sec). Power dissipation of Iron should be smaller than 15W, and temperature should be controllable. Surface temperature of the device should be under 230°C.

**● REWORK**

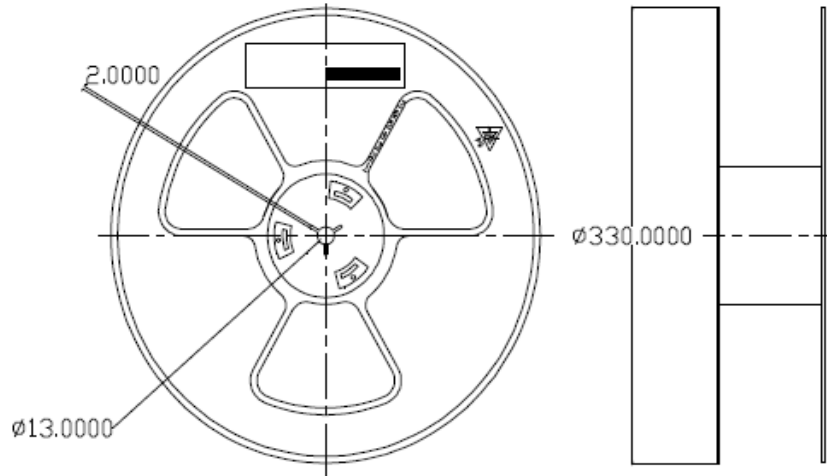
- Customer must finish rework within 3 sec. under 350°C.
- The head of soldering iron cannot touch copper foil.



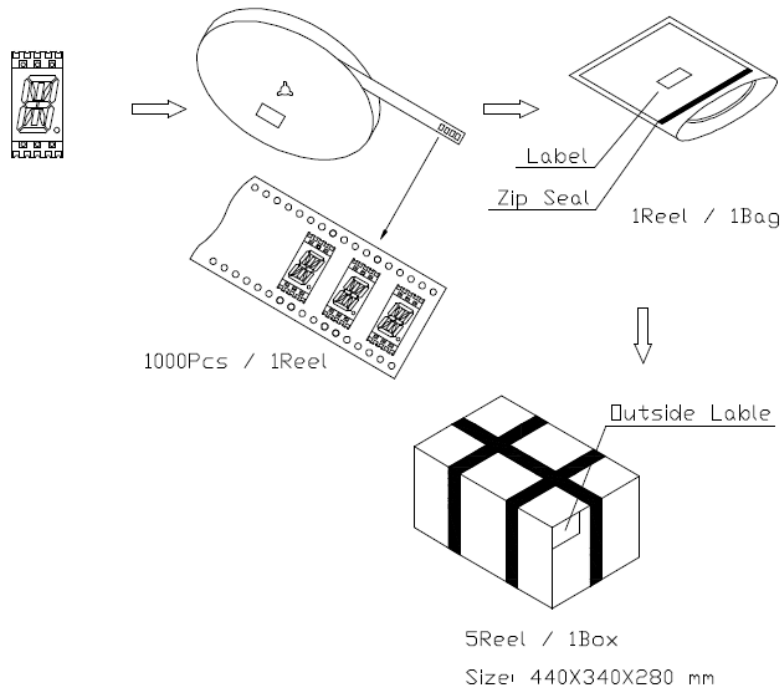
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**PACKAGING SPECIFICATION**

**REEL DIMENSION**



**Packing & Label Specifications**



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